

- ◇ Low current rectification
- ◇ Low forward voltage
- ◇ **SOD923** Micro SMD package (Fig-1) Dimensions:
1.0 mm x 0.6 mm (0.039" x 0.024")
- ◇ RoHS compliant
- ◇ UL-94 V-0 / Green EMC
- ◇ Matte Tin Lead finish (Pb-Free)
- ◇ Moisture Level Sensitivity 1
- ◇ Cathode Band / Device marking:

Device Marking Code	
RB521CS-30	F



Fig -1 Package **SOD923**

Absolute Maximum Ratings (Ta = 25 °C)

Symbol	Parameter	Value	Units
V_{RRM}	Repetitive Peak Reverse Voltage	30	V
V_R	Reverse Voltage	30	V
I_0	Continuous Forward Current	100	mA
I_{FSM}	Non-Repetitive Peak Forward Current *1	500	mA
T_J	Junction Temperature	125	°C
T_{STG}	Storage Temperature	-55 to +125	°C

*1: 8.3ms Single Half Sine-Wave

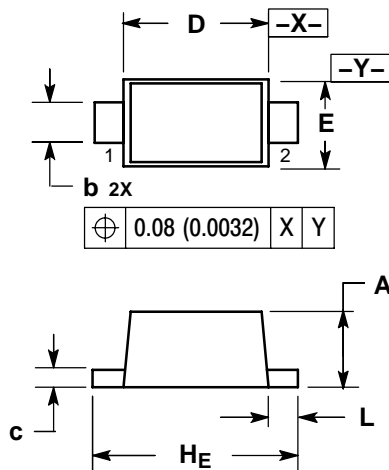
Electrical Characteristics (Ta = 25 °C)

Symbol	Parameter	Conditions	Min	TYP	Max	Units
V_F	Forward Voltage	$I_F = 10mA$			0.35	V
		$I_F = 100mA$			0.55	V
BV_R	Breakdown Voltage	$I_R = 100\mu A$	30			V
I_R	Reverse Current	$V_R = 10V$			10	μA
		$V_R = 30V$			50	μA

Ordering Information

Device	Package	Shipping	Tape wide	Embos pitch	Tape specification	Notes
RB521CS-30	SOD923	8,000 pcs / 7" Reel	8 mm	2 mm	Conductive	

SOD-923

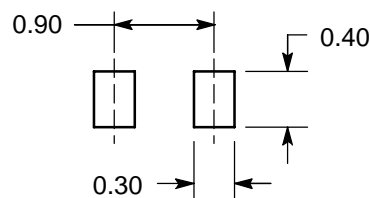


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS